

IN THE SPECIFICATION:

Please amend paragraph number [0027] as follows:

[0027] To align the semiconductor device 14 with the printed circuit board 10 such that discrete conductive elements 20 of the semiconductor device 14 appropriately interface with corresponding terminal pads 16, locating pins 32 are placed in the holes 18' of the printed circuit board 10 and in the apertures 22 of the semiconductor device 14. The locating pins 32 are appropriately sized to fit in the holes 18' and apertures 22 and may be formed such that a ~~press-fit-type~~ fit-type connection is formed upon insertion of the locating pins 32. Prior to assembly of the semiconductor device 14 to the printed circuit board 10, the locating pins 32 may be placed into either the holes 18' or the apertures 22. However, in such a method of assembly, it is preferable that the locating pins 32 be placed into holes 18' of the printed circuit board 10 such that the locating pins 32 may be sighted through the apertures 22 of the semiconductor device 14 during an alignment and assembly operation. Alternatively, the semiconductor device 14 may be placed on the printed circuit board 10 and roughly aligned by sighting through the apertures 22 to the holes 18'. Actual alignment of semiconductor device 14 to printed circuit board 10 would then be effected by subsequently placing the locating pins 32 through both apertures 22 and holes 18'.

Please amend paragraph number [0033] as follows:

[0033] Just as the locating pins 32 may be utilized according to various embodiments, various sizes, shapes and arrangements of the apertures 22 (and thus the corresponding alignment features 18) may be utilized. Figures 5A, 5B and 5C depict some examples of different embodiments which may be used. Figure 5A shows a semiconductor device 14' wherein ~~notch-shaped~~ notch-shaped channels 44 are formed at the periphery of the semiconductor device 14'. It is noted that the channels 44 are shown to have a semicircular shape as shown in this view. Other shapes, such as a simple notched "V", "V," may also be sufficient. The channels 44 still pass from the non-mounting side 28' to the mounting side (not shown) of semiconductor device 14'. Figure 5B shows a semiconductor device 14'' where the channels 46 and 46' are arranged asymmetrically with respect to the geographical outline of the semiconductor device 14'' to facilitate proper

rotational alignment of components. Figure 5C depicts a semiconductor device 14''' having a channel of a first size 48 and a channel of a second size 48' to facilitate proper rotational alignment of components. Thus, the embodiments shown in Figures 5B and 5C not only facilitate proper alignment of the semiconductor device with the printed circuit board, but also ensure proper orientation of a semiconductor device with respect to the printed circuit board. Of course, in utilizing any of the embodiments described above, the alignment features 18 of the printed circuit board 10 are formed to correspond to the size, shape or arrangement of the apertures or channels of the semiconductor device. It is also noted that variations and combinations of the ~~above-described~~ above-described embodiments are contemplated as being within the scope of the invention. As an example, channels of different sizes may be arranged asymmetrically, or along the periphery.